



Surface Mount Pin-Ball BGA/LGA Sockets for 1.00mm & 1.27mm Pitch Packages

FEATURES:

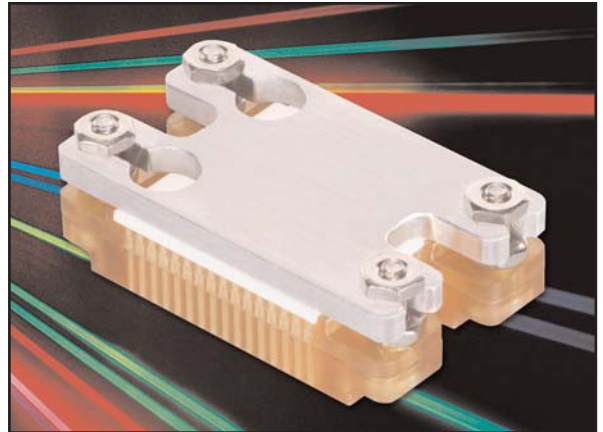
- For applications using BGA, LGA, CSP and other devices on 1.00mm, 1.27mm or larger pitch.
- The 2-bolt version can accommodate any footprint for 15mm or smaller package devices.
- The 4-bolt version can accommodate any footprint from 16mm-50mm package devices.
- The sockets are provided with 2 alignment pins for accurate placement on new application PCB's -or- without alignment pins, for use with existing application PCB's.
- Sockets offer PCB space saving "Side-by-Side" design, allowing multiple sockets to be mounted next to each other and not to take up any more room than the width of the device.
- At the socket bolt-down ends, a 2mm height clearance is provided for component placement near the device.
- Reliable spring probe contact technology is incorporated, with 63/37 Sn/Pb solderballs at the PCB mating side, and a male spring probe on the device mating side.
- Supplied with a standard Aluminum lid, or available with an Aries standard, or customer special heatsink.
- Socket top interposer provides two chip guides to help align the device with the spring probes and provide a positive lid compression stop to accurately control the spring probe deflection.
- Lid slides on and off easily with a few quick turns of the ND-2/56 nut driver tool, supplied with each order.
- Minimal space is used for the socket bolt tabs, to allow for maximum component space around the socket.

SPECIFICATIONS:

- Socket Top and Bottom Interposers = Glass Filled UL94V-0 Ultem.
- Socket Lid or Heat Sink = Aluminum.
- Spring Probe Spring = H.T. Beryllium Coppy Alloy with 30u" min. Gold over 30u" min. Nickel.
- Spring Probe Pins = Brass Alloy with 30u" min. Gold over 30u" min. Nickel.
- Hardware = Stainless Steel.
- Spring Probe Solderballs = .025" Dia. 63/37 Sn/Pb Eutectic Solderballs.
- Spring Probe Contact Force = 17g/Contact (Nominal).
- Estimated Spring Probe Life = 25,000 cycles.
- Operating Temperature Range = -55°C to +125°C (-67°F to +257°F).
- Nut Torque = Supplied with each design.

MOUNTING CONSIDERATIONS:

- Standard BGA device soldering procedures can be followed.
- A socket and footprint drawing with PCB socket layout details will be provided with each order.
- Suggested PCB solder pad size = .030" (.076mm) dia.

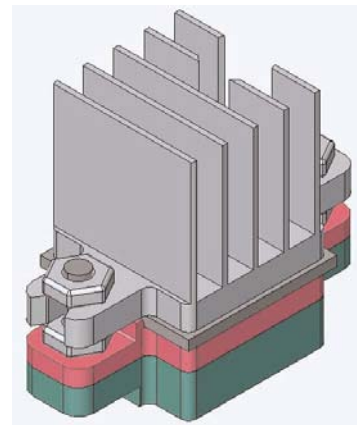


Note: Aries specializes in custom design and production. In addition to the standard products shown on this page, special materials, platings, sizes, and configurations can be furnished, depending on quantities. Aries reserves the right to change product specifications without notice.

ORDERING INFORMATION

CONSULT FACTORY

**For Pin-Ball Nut Driver Tool
Order Part number ND-2/56**



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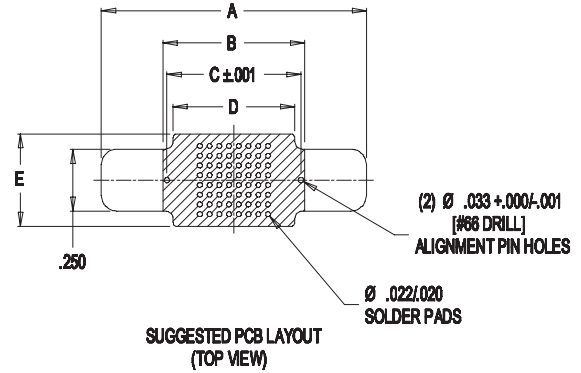
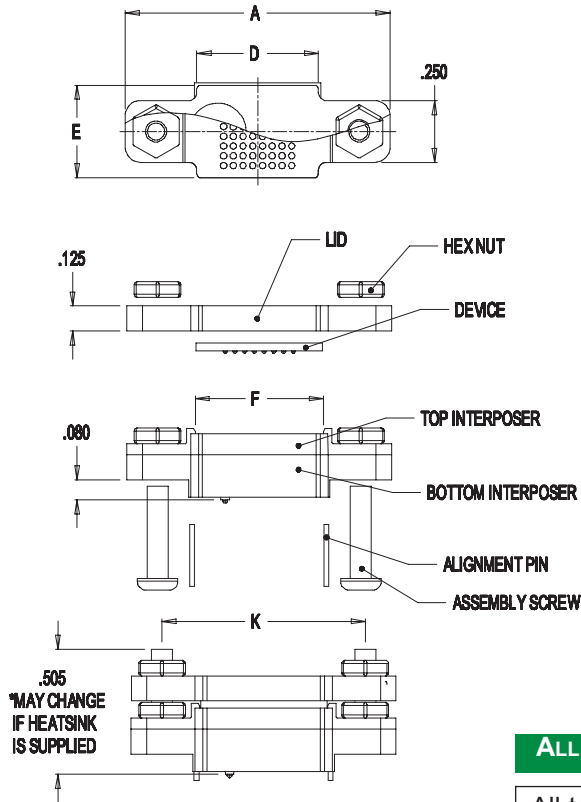
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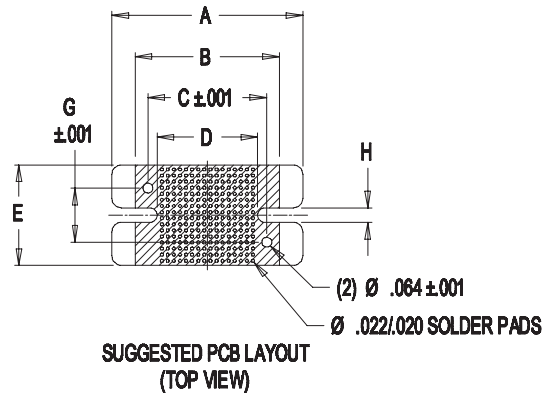
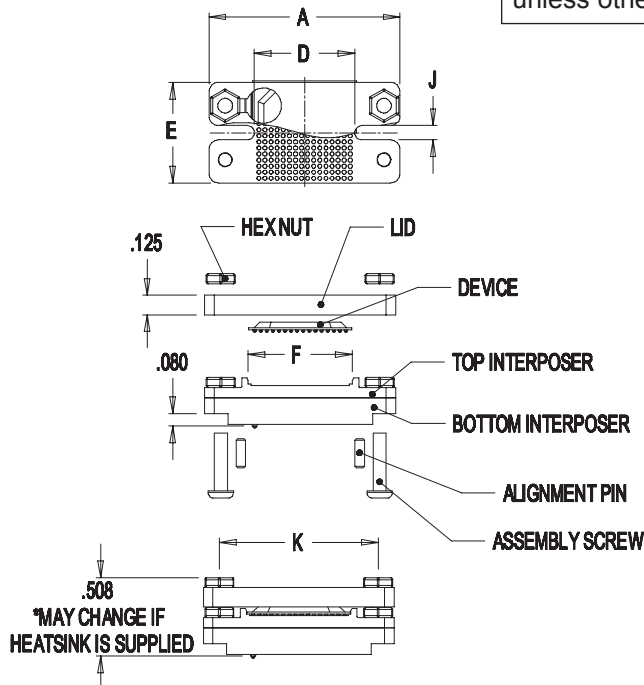
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2 BOLT UP TO 15MM

ALL DIMENSIONS: INCHES [MILLIMETERS]

All tolerances $\pm .005$ [.13] unless otherwise specified



4 BOLT 16 TO 50MM

